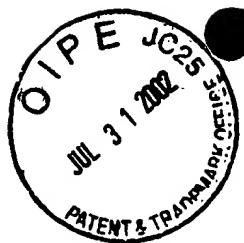


TS99-149B



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Application No. 09/755,282

Gp 12827

July 23, 2002

TO: Commissioner of Patents and Trademarks
Washington, D.C. 20231

FROM: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/755,282
File Date: 01/08/01
Inventor: CHEN, SHENG-HSIUNG
Examiner: MITCHELL, JAMES
Art Unit: 2827
Title: METHOD OF IMPROVING COPPER PAD ADHESION

#9/C
Andy
J. Mitchell
RECEIVED
JULY 1 2002
TECHNOLOGY CENTER 2800

RESPONSE TO OFFICE ACTION

This is in response to the office action dated May 23, 2002.

Please amend the above identified Divisional Application for
patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on July 23, 2002.

Signature

Date:

7/23/02

Stephen B. Ackerman, Reg. No. 37,761